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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL. NUM 10081796	FILING DATE 02/22/2002	CLASS 204	SUBCLASS 192.12	GAU 1753	EXAMINER McDonald
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**CONTINUING DATA VERIFIED:
THIS APPLICATION IS A DIV OF 09/261,879 03/02/1999

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	ATTORNEY DOCKET NO SC91135A D01
TITLE : Method for forming a barrier layer for use in a copper interconnect			

U.S. DEPT. OF COMM /PAT. & TM-PTO-436L (Rev. 12-94)

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NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
TERMINAL DISCLAIMER		Primary Examiner		
		Application Examiner		
PREPARED FOR ISSUE				
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